HLMP-LG65-xxxxx

Precision Optical Performance Red
New 4mm Standard Oval LEDs

Data Sheet

Lead (Pb) Free
RoHS 6 fully
compliant

Description

This Precision Optical Performance Oval LED is specifically designed for full color/video and passenger information signs. The oval shaped radiation pattern and high luminous intensity ensure that these devices are excellent for wide field of view outdoor applications where a wide viewing angle and readability in sunlight are essential. The package epoxy contains both UV-A and UV-B inhibitors to reduce the effects of long term exposure to direct sunlight.

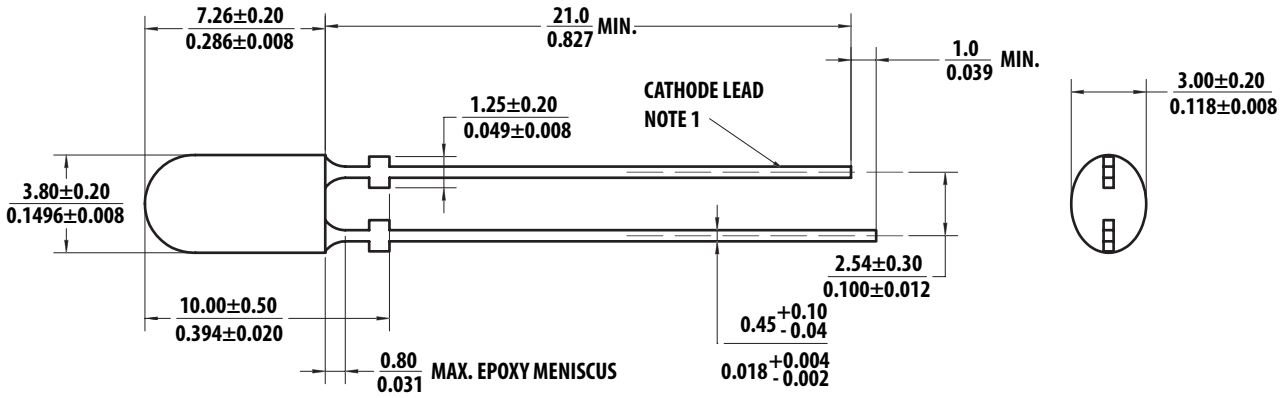
Features

- Well defined spatial radiation pattern
- High brightness material
- Superior resistance to moisture
- Standoff Package
- Red Tinted Diffused
- Typical viewing angle 50° x100°

Applications

- Full color signs

Package Dimensions



Notes:
All dimensions in millimeters (inches).
Tolerance is ± 0.20mm unless other specified

Device Selection Guide

Part Number	Color and Dominant Wavelength λd (nm) Typ [3]	Luminous Intensity Iv,- (mcd) at 20 mA [1,2,4]	
		Min.	Max.
HLMP-LG65-VY0DD	Red 626	1150	2400
HLMP-LG65-WX0DD	Red 626	1380	1990
HLMP-LG65-WZ0DD	Red 626	1380	2900

Notes:
1. The luminous intensity is measured on the mechanical axis of the lamp package and it is tested with pulsing condition.
2. The optical axis is closely aligned with the package mechanical axis.
3. Dominant wavelength, λd, is derived from the CIE Chromaticity Diagram and represents the color of the lamp.
4. Tolerance for each bin limit is ± 15%.

Absolute Maximum Ratings

$T_J = 25°C$

Parameter	Red	Unit
DC Forward Current [1]	50	mA
Peak Forward Current	100 [2]	mA
Power Dissipation	130	mW
Reverse Voltage	5	V
LED Junction Temperature	130	°C
Operating Temperature Range	-40 to +100	°C
Storage Temperature Range	-40 to +100	°C

Notes:
1. Derate linearly as shown in Figure 4.
2. Duty Factor 30%, frequency 1KHz.

Electrical / Optical Characteristics

$T_J = 25°C$

Parameter	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Forward Voltage	V_F	1.8	2.1	2.4	V	$I_F = 20$ mA
Reverse Voltage	V_R	5			V	$I_R = 100$ µA
Dominant Wavelength[1]	λ_d	618	626	630	nm	$I_F = 20$ mA
Peak Wavelength	λ_{PEAK}		634		nm	Peak of Wavelength of Spectral Distribution at $I_F = 20$ mA
Thermal Resistance	$R\theta_{J\text{-}PIN}$		240		°C/W	LED Junction-to-Anode lead
Luminous Efficacy [2]	η_V		150		lm/W	Emitted Luminous Power/Emitted Radiant Power

Notes:
1. The dominant wavelength is derived from the chromaticity Diagram and represents the color of the lamp
2. The radiant intensity, I_e in watts per steradian, may be found from the equation $I_e = I_V/\eta_V$ where I_V is the luminous intensity in candelas and η_V is the luminous efficacy in lumens/watt.

AlInGaP Red

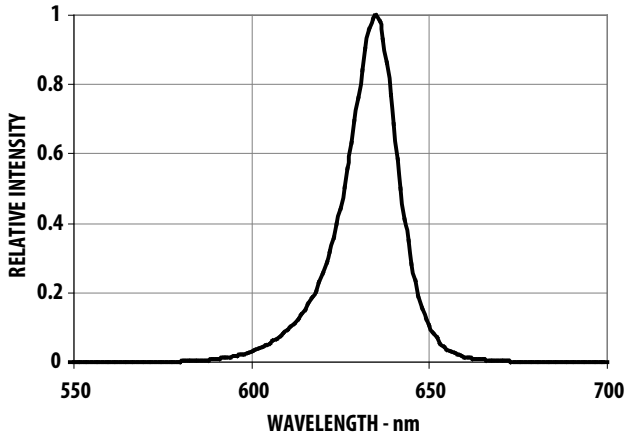


Figure 1. Relative Intensity vs Wavelength

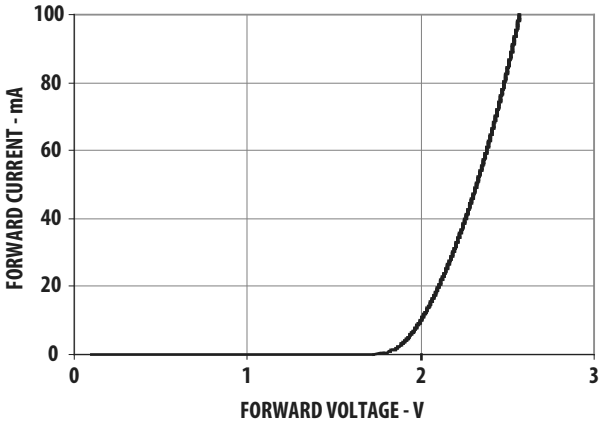


Figure 2. Forward Current vs Forward Voltage

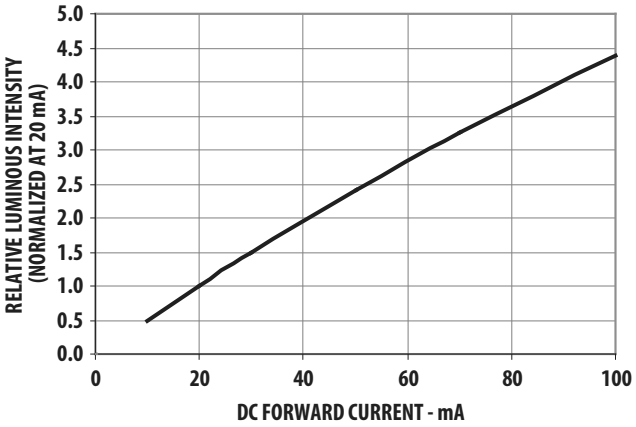


Figure 3. Relative Intensity vs Forward Current

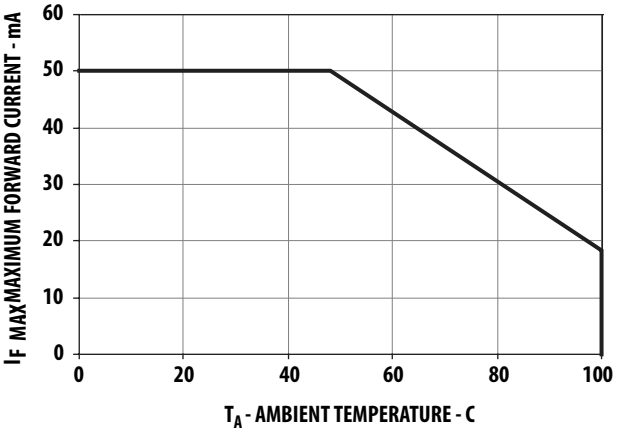


Figure 4. Maximum Forward Current vs Ambient Temperature

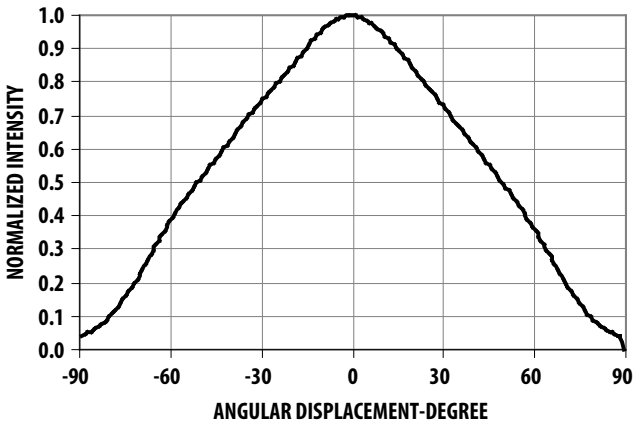


Figure 5. Radiation pattern-Major Axis

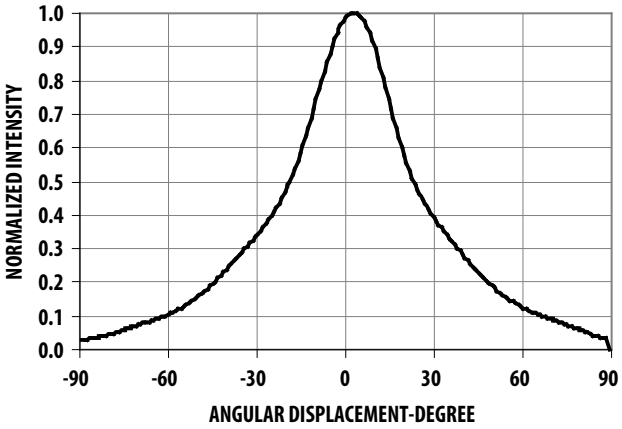


Figure 6. Radiation pattern-Minor Axis

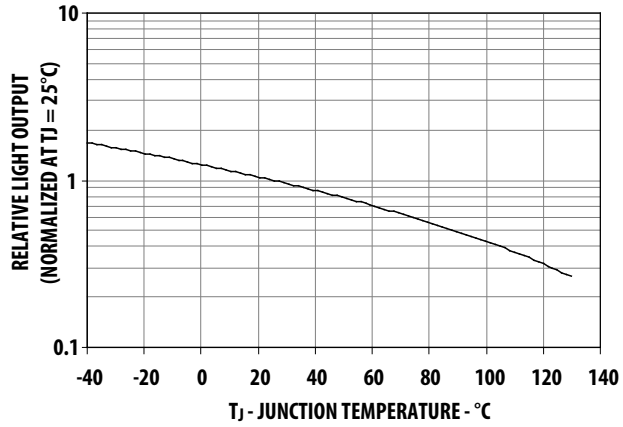


Figure 7. Relative Light Output vs Junction Temperature

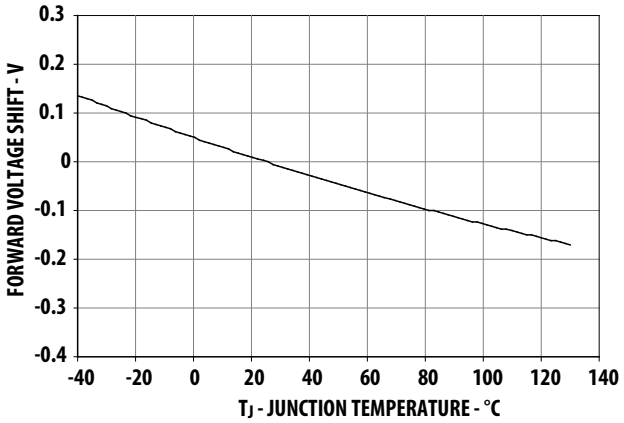


Figure 8. Relative Forward Voltage Shift vs Junction Temperature

Intensity Bin Limit Table (1.2: 1 Iv Bin Ratio)

	Intensity (mcd) at 20 mA	
Bin	**Min**	**Max**
V	1150	1380
W	1380	1660
X	1660	1990
Y	1990	2400
Z	2400	2900

Tolerance for each bin limit is ± 15%

Red Color Range

Min Dom	Max Dom	Xmin	Ymin	Xmax	Ymax
618	630	0.6872	0.3126	0.6890	0.2943
		0.6690	0.3149	0.7080	0.2920

Tolerance for each bin limit is ± 0.5nm

V_F Bin Table (V at 20mA)

Bin ID	Min	Max
VD	1.8	2.0
VA	2.0	2.2
VB	2.2	2.4

Notes:
1. Tolerance for each bin limit is ±0.05V
2. VF binning only applicable to Red color.

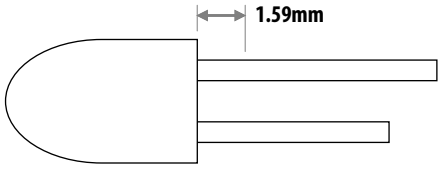
Precautions:

Lead Forming:

- The leads of an LED lamp may be preformed or cut to length prior to insertion and soldering on PC board.
- For better control, it is recommended to use proper tool to precisely form and cut the leads to applicable length rather than doing it manually.
- If manual lead cutting is necessary, cut the leads after the soldering process. The solder connection forms a mechanical ground which prevents mechanical stress due to lead cutting from traveling into LED package. This is highly recommended for hand solder operation, as the excess lead length also acts as small heat sink.

Soldering and Handling:

- Care must be taken during PCB assembly and soldering process to prevent damage to the LED component.
- LED component may be effectively hand soldered to PCB. However, it is only recommended under unavoidable circumstances such as rework. The closest manual soldering distance of the soldering heat source (soldering iron's tip) to the body is 1.59mm. Soldering the LED using soldering iron tip closer than 1.59mm might damage the LED.



- ESD precaution must be properly applied on the soldering station and personnel to prevent ESD damage to the LED component that is ESD sensitive. Do refer to Avago application note AN 1142 for details. The soldering iron used should have grounded tip to ensure electrostatic charge is properly grounded.
- Recommended soldering condition:

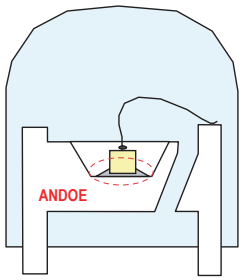
	Wave Soldering [1, 2]	Manual Solder Dipping
Pre-heat temperature	105°C Max.	-
Preheat time	60 sec Max	-
Peak temperature	260°C Max.	260°C Max.
Dwell time	5 sec Max.	5 sec Max

Note:
1. Above conditions refers to measurement with thermocouple mounted at the bottom of PCB.
2. It is recommended to use only bottom preheaters in order to reduce thermal stress experienced by LED.

- Wave soldering parameters must be set and maintained according to the recommended temperature and dwell time. Customer is advised to perform daily check on the soldering profile to ensure that it is always conforming to recommended soldering conditions.

Note:
1. PCB with different size and design (component density) will have different heat mass (heat capacity). This might cause a change in temperature experienced by the board if same wave soldering setting is used. So, it is recommended to re-calibrate the soldering profile again before loading a new type of PCB.
2. Avago Technologies' high brightness LED are using high efficiency LED die with single wire bond as shown below. Customer is advised to take extra precaution during wave soldering to ensure that the maximum wave temperature does not exceed 260°C and the solder contact time does not exceeding 5sec. Over-stressing the LED during soldering process might cause premature failure to the LED due to delamination.

Avago Technologies LED Configuration



AlInGaP Device

Note: Electrical connection between bottom surface of LED die and the lead frame is achieved through conductive paste.

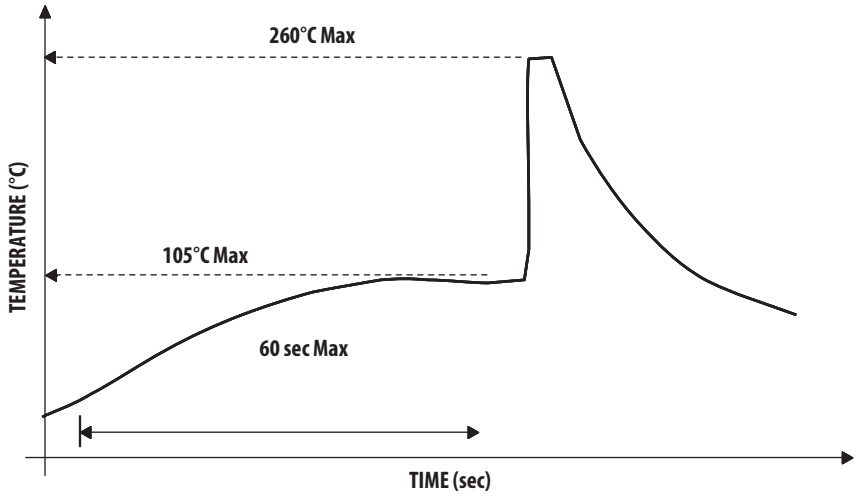
- Any alignment fixture that is being applied during wave soldering should be loosely fitted and should not apply weight or force on LED. Non metal material is recommended as it will absorb less heat during wave soldering process.
- At elevated temperature, LED is more susceptible to mechanical stress. Therefore, PCB must allowed to cool down to room temperature prior to handling, which includes removal of alignment fixture or pallet.
- If PCB board contains both through hole (TH) LED and other surface mount components, it is recommended that surface mount components be soldered on the top side of the PCB. If surface mount need to be on the bottom side, these components should be soldered using reflow soldering prior to insertion the TH LED.
- Recommended PC board plated through holes (PTH) size for LED component leads.

LED component lead size	Diagonal	Plated through hole diameter
0.45 x 0.45 mm (0.018x 0.018 inch)	0.636 mm (0.025 inch)	0.98 to 1.08 mm (0.039 to 0.043 inch)
0.50 x 0.50 mm (0.020x 0.020 inch)	0.707 mm (0.028 inch)	1.05 to 1.15 mm (0.041 to 0.045 inch)

- Over-sizing the PTH can lead to twisted LED after clinching. On the other hand under sizing the PTH can cause difficulty inserting the TH LED.

Refer to application note AN5334 for more information about soldering and handling of high brightness TH LED lamps.

Example of Wave Soldering Temperature Profile for TH LED



Recommended solder:
Sn63 (Leaded solder alloy)
SAC305 (Lead free solder alloy)

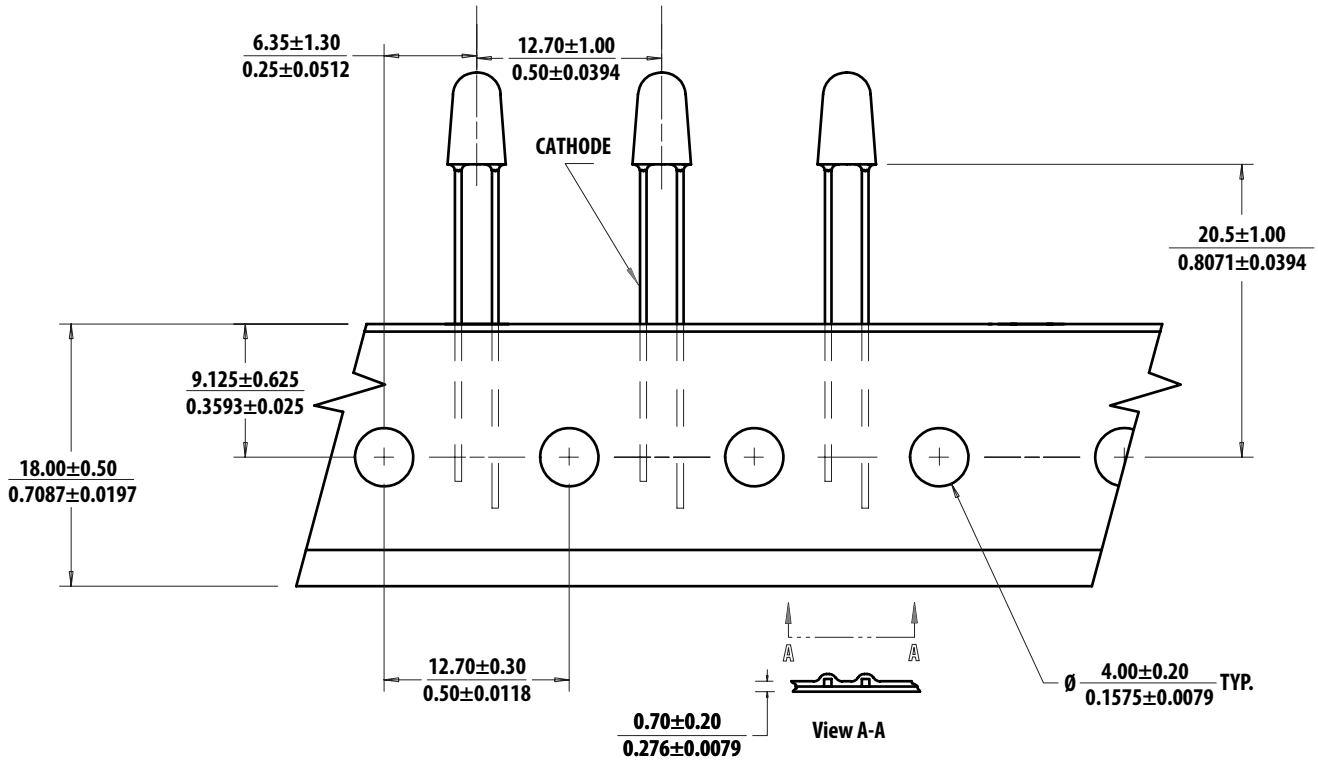
Flux: Rosin flux

Solder bath temperature: 255°C ± 5°C
(maximum peak temperature = 260°C)

Dwell time: 3.0 sec - 5.0 sec
(maximum = 5sec)

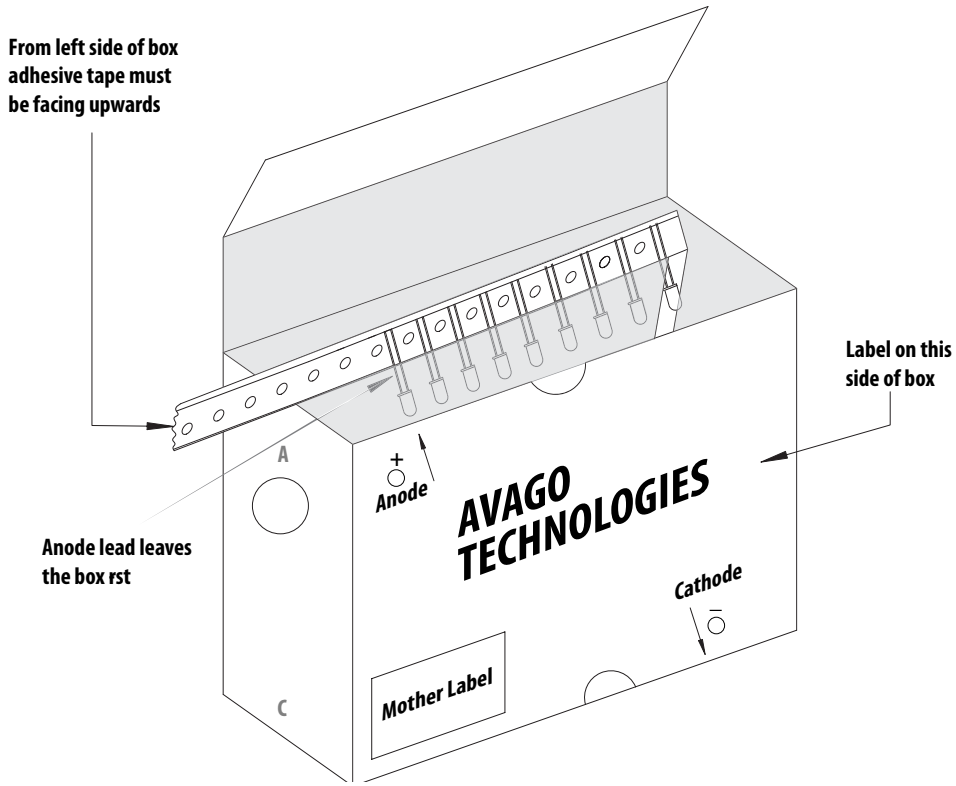
Note: Allow for board to be sufficiently cooled to room temperature before exerting mechanical force.

Ammo Packs Drawing



Note: The ammo-packs drawing is applicable for packaging option –DD & -ZZ and regardless standoff or non-standoff

Packaging Box for Ammo Packs

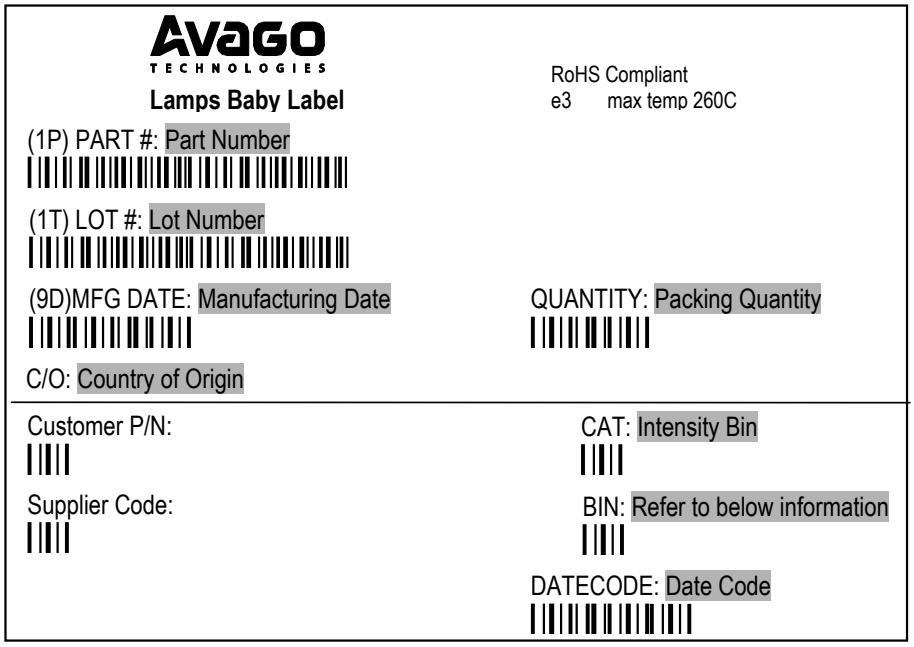


Note: For InGaN device, the ammo pack packaging box contain ESD logo

Packaging Label

(i) Avago Mother Label: (Available on packaging box of ammo pack and shipping box)

(ii) Avago Baby Label (Only available on bulk packaging)



Acronyms and Definition:

BIN:

(i) Color bin only or VF bin only (Applicable for part number with color bins but without VF bin OR part number with VF bins and no color bin)

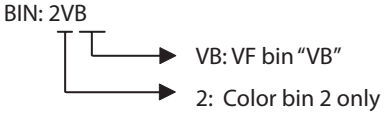
OR

(ii) Color bin incorporated with VF Bin (Applicable for part number that have both color bin and VF bin)

Example:

(i) Color bin only or VF bin only
BIN: 2 (represent color bin 2 only)
BIN: VB (represent VF bin "VB" only)

(ii) Color bin incorporate with VF Bin



For product information and a complete list of distributors, please go to our web site: **www.avagotech.com**

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